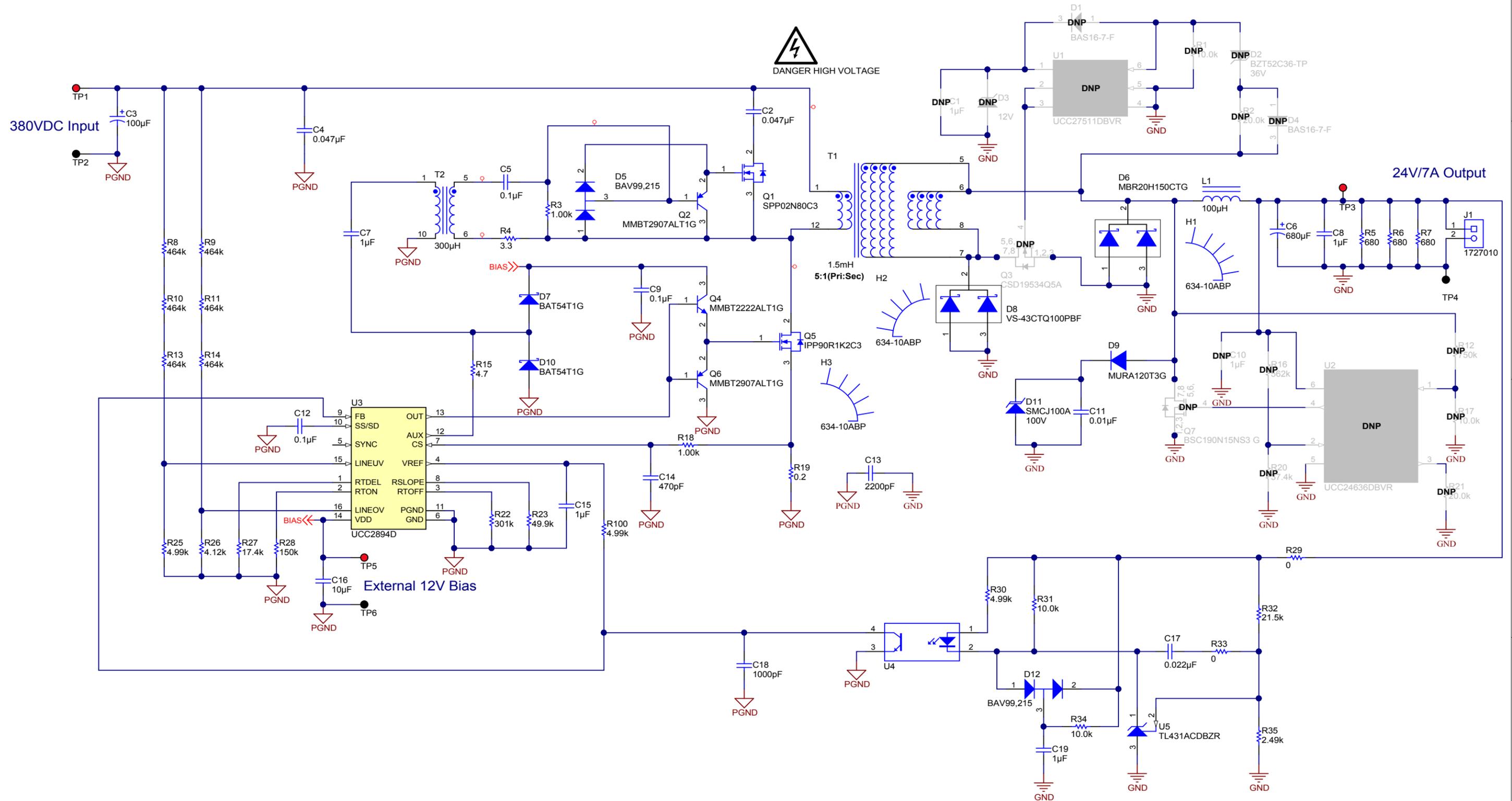


Assembly Notes:

1. Built on PMP7931 Rev B PCB.
2. R100 was added for Rev C.

SUSTAINED LOADS >5A REQUIRE FORCED AIR COOLING



PCB Number: PMP7391
PCB Rev: B

Orderable: N/A	Designed for: Project Title: 380VDCin, 24V/7A Active Clamp Forward	Mod. Date: 12/11/2015
TID #: Number: PMP7391	Rev: C	Sheet Title: Assembly Variant001
Version control disabled	Drawn By: B King	Sheet: 1 of 1
File: PMP7391_REV.C_SchDoc	Size: B	Contact: http://www.ti.com/support

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